

Bill of Materia

TI DESIGNS

TIDM-BIOSIGNMONITOR

ltem	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1			Printed Circuit Board					
2		STD		Test Point, O.025"				TP_25MIL-SM	
3		STD		Test Point, O.025"				TP_25MIL-SM	
4		STD		Test Point, O.025"				TP_25MIL-SM	
5	1	STD		Test Point, O.025"				TP_25MIL-SM	
6	1	STD		Test Point, O.025"				TP_25MIL-SM	
7	1	STD		Test Point, O.025"				TP_25MIL-SM	
8	1	STD		Test Point, O.025"				TP_25MIL-SM	1
9	1	STD		Test Point, O.025"				TP_25MIL-SM	,
10	1	STD		Test Point, O.025"				TP_25MIL-SM	
11	1	STD		Test Point, O.025"				TP 25MIL-SM	
12	1	STD		Test Point, O.025"				TP_25MIL-SM	
13	1	STD		Test Point, O.025"				TP 25MIL-SM	
14		STD		Test Point, O.025"				TP_25MIL-SM	
15		STD		Test Point, O.025"				TP 25MIL-SM	
16		STD		Test Point, O.025"				TP 25MIL-SM	
17		STD		Test Point, O.025"				TP 25MIL-SM	
18		STD		Test Point, O.025"				TP 25MIL-SM	
19		STD		Test Point, 0.025"				TP 25MIL-SM	
20		STD		Test Point, 0.025"				TP 25MIL-SM	
21		STD		Test Point, O.025"				TP 25MIL-SM	
22		10uF		CAP, TA, 10 µF, 10 V, +/- 10%, 3.4 ohm, SMD	Vishay Sprague	293D106X9010A2TE	293D106X9010A2TE3		
23	1	10uF		CAP, TA, 10 µF, 10 V, +/- 10%, 3.4 ohm, SMD	Vishay Sprague	293D106X9010A2TE	293D106X9010A2TE3	3216-18	
24	1	1uF		CAP, CERM, 1 µF, 6.3 V, +/- 20%, X5R, 0402	TDK Corporation	C1005X5R0J105M05	C1005X5R0J105M050	0402	
25		2.2uF		CAP, CERM, 2.2 μF, 16 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1C225K05		0402	
26		0.1uF		CAP, CERM, 0.1 μF, 10 V, +/- 10%, X5R, 0402	TDK Corporation		C1005X5R1A104K050		
27		0.1uF		CAP, CERM, 0.1 μF, 10 V, +/- 10%, X5R, 0402	TDK Corporation		C1005X5R1A104K050		
28		0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation		C1005X5R1A104K050		
29		0.01uF		CAP, CERM, 0.01 µF, 25 V, +/- 10%, X7R, 0402	TDK Corporation	C1005X7R1E103K05		0402	i
30		1uF 0.1uF		CAP, TA, 1 µF, 16 V, +/- 10%, 9.3 ohm, SMD	Vishay Sprague TDK Corporation		293D105X9016A2TE3 C1005X5R1A104K050		
31		0.1uF 0.1uF		CAP, CERM, 0.1 μF, 10 V, +/- 10%, X5R, 0402 CAP, CERM, 0.1 μF, 10 V, +/- 10%, X5R, 0402	TDK Corporation		C1005X5R1A104K050		
33		10uF		CAP, TA, 10 µF, 10 V, +/- 10%, X3K, 0402	Vishay Sprague		293D106X9010A2TE3		
34		0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, 3.4 01111, 31112	TDK Corporation		C1005X5R1A104K050		
35		0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation		C1005X5R1A104K050		

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
36	1	1uF		CAP, TA, 1 µF, 16 V, +/- 10%, 9.3 ohm, SMD	Vishay Sprague	293D105X9016A2TE	293D105X9016A2TE3	3216-18	
37	1	10uF		CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0402	Samsung Electro-M	CL05A106MQ5NUNC	Loading	0402	
38	1	10uF		CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0402		CL05A106MQ5NUNC		0402	
39	1	0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1A104K05	C1005X5R1A104K05	0402	
40	1	0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1A104K05	C1005X5R1A104K05	0402	
41	1	2.2uF		CAP, CERM, 2.2 µF, 16 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1C225K05	Loading	0402	
42	1	10uF		CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0402	Samsung Electro-M	CL05A106MQ5NUNC	Loading	0402	
43	1	10uF		CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0402		CL05A106MQ5NUNC		0402	
44		0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402			C1005X5R1A104K05		
45		0.1uF		CAP, CERM, 0.1 μF, 10 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1A104K05	C1005X5R1A104K05		
46	1	2200pF		CAP, CERM, 2200 pF, 50 V, +/- 10%, X8R, 0402		C1005X8R1H222K05		0402	
47	1	0.01uF		CAP, CERM, 0.01 µF, 25 V, +/- 10%, X7R, 0402	TDK Corporation	C1005X7R1E103K05	Loading	0402	
48	1	1uF		CAP, CERM, 1 µF, 6.3 V, +/- 20%, X5R, 0402	TDK Corporation	C1005X5R0J105M05	C1005X5R0J105M05	0402	
49		0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation		C1005X5R1A104K05		
50	1	0.47uF		CAP, CERM, 0.47 µF, 6.3 V, +/- 10%, X5R, 0402	Murata Electronics	GRM155R60J474KE1	GRM155R60J474KE1	0402	
51	1	33pF		CAP, CERM, 33 pF, 50 V, +/- 5%, C0G/NP0, 0603	TDK Corporation	C1608C0G1H330J08	C1608C0G1H330J08	0603	
52		100uF		CAP, CERM, 100 µF, 10 V, +/- 20%, X5R, 1206_190	TDK Corporation	C3216X5R1A107M16	C3216X5R1A107M16	1206_190	
53	1	10uF		CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0402	Samsung Electro-M	CL05A106MQ5NUNC	Loading	0402	
54	1	10uF		CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0402	Samsung Electro-M	CL05A106MQ5NUNC	Loading	0402	
55	1	0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1A104K05	C1005X5R1A104K05	0402	
56	1	0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1A104K05	C1005X5R1A104K05	0402	
57	1	0.01uF		CAP, CERM, 0.01 µF, 25 V, +/- 10%, X7R, 0402	TDK Corporation	C1005X7R1E103K05	Loading	0402	
58	1	1uF		CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1C105K05	C1005X5R1C105K05	0402	
59	1	0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation		C1005X5R1A104K05		
60	1	1uF		CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1C105K05	C1005X5R1C105K05	0402	
61	1	0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation		C1005X5R1A104K05		
62	1	1500pF		CAP, CERM, 1500 pF, 50 V, +/- 10%, X7R, 0603	Kemet	C0603C152K5RACTU	C0603C152K5RACTU	0603	
63	1	3000pF		CAP, CERM, 3000 pF, 50 V, +/- 5%, C0G/NP0, 0603			GRM1885C1H302JA0		
64		4700pF		CAP, CERM, 4700 pF, 10 V, +/- 10%, X5R, 0402			GRM155R61A472KA	0402	
65	1	2200pF		CAP, CERM, 2200 pF, 50 V, +/- 10%, X8R, 0402	TDK Corporation	C1005X8R1H222K05	Loading	0402	
66	1	4700pF		CAP, CERM, 4700 pF, 10 V, +/- 10%, X5R, 0402	•		GRM155R61A472KA	0402	
67		0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1A104K05	C1005X5R1A104K05	0402	
68	1	2200pF		CAP, CERM, 2200 pF, 50 V, +/- 10%, X8R, 0402	TDK Corporation	C1005X8R1H222K05	Loading	0402	
69	1	0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1A104K05	C1005X5R1A104K05	0402	
70	1	10uF		CAP, CERM, 10 µF, 6.3 V, +/- 20%, X5R, 0603	TDK Corporation	C1608X5R0J106M08		0603	
71	1	0.1uF		CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0402	TDK Corporation	C1005X5R1A104K05	C1005X5R1A104K05	0402	
72	1	2200pF		CAP, CERM, 2200 pF, 50 V, +/- 10%, X8R, 0402	TDK Corporation	C1005X8R1H222K05	Loading	0402	
73	1	2200pF		CAP, CERM, 2200 pF, 50 V, +/- 10%, X8R, 0402		C1005X8R1H222K05	Loading	0402	
74	1	1uF		CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0402			C1005X5R1C105K05	0402	
75		1uF		CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0402	TDK Corporation		C1005X5R1C105K05		
76		3000pF		CAP, CERM, 3000 pF, 50 V, +/- 5%, C0G/NP0, 0603			GRM1885C1H302JA0		
77		10pF		CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0603	AVX Corporation	06035A100JAT2A	06035A100JAT2A	0603	
78		10pF		CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0603		06035A100JAT2A	06035A100JAT2A	0603	
79		35V		Diode, Schottky, 35V, 0.1A, SOD-523F	Comchip Technolog		CDBU0130L	SOD-523F	
80		35V		Diode, Schottky, 35V, 0.1A, SOD-523F	Comchip Technolog		CDBU0130L	SOD-523F	
81		600 ohm		Ferrite Bead, 600 ohm @ 100MHz, 0.2A, 0603		BLM18HG601SN1D		0603	
82		600 ohm		Ferrite Bead, 600 ohm @ 100MHz, 0.2A, 0603		BLM18HG601SN1D		0603	
83		600 ohm	1	Ferrite Bead, 600 ohm @ 100MHz, 0.2A, 0603		BLM18HG601SN1D		0603	

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
84	1	600 ohm		Ferrite Bead, 600 ohm @ 100MHz, 0.2A, 0603	Murata Electronics	BLM18HG601SN1D	BLM18HG601SN1D	0603	
85		600 ohm				BLM18HG601SN1D		0603	
86		600 ohm				BLM18HG601SN1D			
87		4.7uH		Inductor, Shielded, Ferrite, 4.7uH, 1.2A, 0.14 ohm, SM				EPL3015	
88	1			RES, 0, 5%, 0.063 W, 0402	Panasonic Electron	FRJ-2GF0R00X		0402	
89	1				Panasonic Electron	FRJ-2GF0R00X		0402	
90	1				Panasonic Electron			0402	
91	1			RES, 0, 5%, 0.063 W, 0402	Panasonic Electron			0402	
92		47k		RES, 47 k, 5%, 0.063 W, 0402		CRCW040247K0JNE			
93	1				Panasonic Electron			0402	
94		21.5k		RES, 21.5 k, 1%, 0.063 W, 0402		CRCW040221K5FKE			
95		10.0k		RES, 10.0 k, 1%, 0.063 W, 0402	Vishay Dale		CRCW040210K0FKE		
96	1	1.00Meg		RES, 1.00 M, 1%, 0.1 W, 0402	Panasonic Electron	ERJ-2RKF1004X		0402	
97		11.8k		RES, 11.8 k, 1%, 0.063 W, 0402		CRCW040211K8FKE		0402	
98		8.06k		RES, 8.06 k, 1%, 0.063 W, 0402		CRCW04028K06FKE			
99	1				Panasonic Electron	ERJ-2GE0R00X		0402	
100	1			RES, 0, 5%, 0.063 W, 0402	Panasonic Electron		ERJ-2GE0R00X	0402	
101		1.00Meg		RES, 1.00 M, 1%, 0.1 W, 0402	Panasonic Electron			0402	
102		200k			Panasonic Electron			0402	
103		4.99k		RES, 4.99 k, 1%, 0.063 W, 0402	Vishay Dale		CRCW04024K99FKE		
104		1.00Meg		RES, 1.00 M, 1%, 0.1 W, 0402	Panasonic Electron			0402	
105	1			RES, 0, 5%, 0.063 W, 0402	Panasonic Electron			0402	
106	1	100k		RES, 100 k, 1%, 0.1 W, 0402	Loading			0402	
107		100k		RES, 100 k, 1%, 0.1 W, 0402	Loading			0402	
108	1	51.1k		RES, 51.1 k, 1%, 0.063 W, 0402	Vishay Dale	CRCW040251K1FKE	CRCW040251K1FKE	0402	
109		10.0Meg		RES, 10.0 M, 1%, 0.063 W, 0402	Vishay Dale		CRCW040210M0FKE		
110		10.0Meg		RES, 10.0 M, 1%, 0.063 W, 0402	Vishay Dale	CRCW040210M0FKE	CRCW040210M0FKE	0402	
111	1	40.2k		RES, 40.2 k, 1%, 0.063 W, 0402	Vishay Dale	CRCW040240K2FKE	CRCW040240K2FKE	0402	
112	1	40.2k		RES, 40.2 k, 1%, 0.063 W, 0402	Vishay Dale	CRCW040240K2FKE	CRCW040240K2FKE	0402	
113	1	10.0Meg		RES, 10.0 M, 1%, 0.063 W, 0402	Vishay Dale	CRCW040210M0FKE	CRCW040210M0FKE	0402	
114	1	10.0Meg		RES, 10.0 M, 1%, 0.063 W, 0402	Vishay Dale	CRCW040210M0FKE	CRCW040210M0FKE	0402	
115	1	51.1k		RES, 51.1 k, 1%, 0.063 W, 0402	Vishay Dale	CRCW040251K1FKE	CRCW040251K1FKE	0402	
116	1	3.3k		RES, 3.3 k, 5%, 0.063 W, 0402	Vishay Dale	CRCW04023K30JNE	CRCW04023K30JNE	0402	
117	1	3.3k		RES, 3.3 k, 5%, 0.063 W, 0402	Vishay Dale	CRCW04023K30JNE	CRCW04023K30JNE	0402	
118	1			Single Output High PSRR LDO, 200 mA, Fixed 3 V Ou	Texas Instruments	TPS73030DBVR	None	DBV0005A_N	
119	1	LMP2231AMF	-E	Single Micropower Precision Op Amp	Texas Instruments			MF05A_L	
120	1			LOW INPUT VOLTAGE STEP-UP CONVERTER IN 6	Texas Instruments	TPS61220DCK	None	DCK0006A_N	
121	1			14 bit, digital, triaxial acceleration sensor with intelliger		BMA280	None	LGA-12P	
122	1			Precision Micropower Shunt Voltage Reference, 3-pin				MF03A_N	
123	1			The Texas Instruments Dynamic NFC Interface Transp				PW0014A_M	
124	1			High-Accuracy, Low-Power, Digital Temperature Sens				DRL0006A	
125	1			Low-Power, 2-Channel, 24-Bit Analog Front-End for Bi				PBS0032A_N	
126	1			Mixed-Signal Microcontrollers, RGC0064B		MSP430FR5889IRGC		RGC0064B	
127	1			Crystal, 32.768kHz, 12.5pF, SMD	EPSON	FC-12M 32.7680KA-A	FC-12M 32.7680KA-A	Epson_FC-12N	
128	0			Battery, Lithium Polymer, 3V, 25mAh	Solicore	Not Applicable		Flat_Battery	
129	0			Battery, Lithium Polymer, 3V, 25mAh	Solicore	Not Applicable		Flat_Battery	
130	0	39pF		CAP, CERM, 39pF, 50V, +/-5%, C0G/NP0, 0402	Murata Electronics	GRM1555C1H390JA	GRM1555C1H390JA0	0402	
131	0			CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageRef	Not Applicable	Not Applicable	Not Applicable	0603	

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
132	0			Fiducial mark. There is nothing to buy or mount.				Fiducial10-20	
133	0			Fiducial mark. There is nothing to buy or mount.				Fiducial10-20	
134	0			Fiducial mark. There is nothing to buy or mount.				Fiducial10-20	
135	0	0		RES, 0, 5%, 0.063 W, 0402	Panasonic Electron	ERJ-2GE0R00X	ERJ-2GE0R00X	0402	
136	0	0		RES, 0, 5%, 0.063 W, 0402	Panasonic Electron	ERJ-2GE0R00X	ERJ-2GE0R00X	0402	

IMPORTANT NOTICE FOR TI REFERENCE DESIGNS

Texas Instruments Incorporated ("TI") reference designs are solely intended to assist designers ("Buyers") who are developing systems that incorporate TI semiconductor products (also referred to herein as "components"). Buyer understands and agrees that Buyer remains responsible for using its independent analysis, evaluation and judgment in designing Buyer's systems and products.

TI reference designs have been created using standard laboratory conditions and engineering practices. TI has not conducted any testing other than that specifically described in the published documentation for a particular reference design. TI may make corrections, enhancements, improvements and other changes to its reference designs.

Buyers are authorized to use TI reference designs with the TI component(s) identified in each particular reference design and to modify the reference design in the development of their end products. HOWEVER, NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY THIRD PARTY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT, IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI REFERENCE DESIGNS ARE PROVIDED "AS IS". TI MAKES NO WARRANTIES OR REPRESENTATIONS WITH REGARD TO THE REFERENCE DESIGNS OR USE OF THE REFERENCE DESIGNS, EXPRESS, IMPLIED OR STATUTORY, INCLUDING ACCURACY OR COMPLETENESS. TI DISCLAIMS ANY WARRANTY OF TITLE AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, QUIET ENJOYMENT, QUIET POSSESSION, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS WITH REGARD TO TI REFERENCE DESIGNS OR USE THEREOF. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY BUYERS AGAINST ANY THIRD PARTY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON A COMBINATION OF COMPONENTS PROVIDED IN A TI REFERENCE DESIGN. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, SPECIAL, INCIDENTAL, CONSEQUENTIAL OR INDIRECT DAMAGES, HOWEVER CAUSED, ON ANY THEORY OF LIABILITY AND WHETHER OR NOT TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES, ARISING IN ANY WAY OUT OF TI REFERENCE DESIGNS OR BUYER'S USE OF TI REFERENCE DESIGNS.

TI reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques for TI components are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

Reproduction of significant portions of TI information in TI data books, data sheets or reference designs is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards that anticipate dangerous failures, monitor failures and their consequences, lessen the likelihood of dangerous failures and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in Buyer's safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed an agreement specifically governing such use.

Only those TI components that TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have *not* been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.